

International IOR Rectifier

PD - 94440

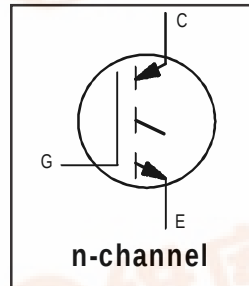
IRG4PC60F-P

INSULATED GATE BIPOLAR TRANSISTOR

Fast Speed IGBT

Features

- Fast: Optimized for medium operating frequencies (1-5 kHz in hard switching, >20 kHz in resonant mode).
- Generation 4 IGBT design provides tighter parameter distribution and higher efficiency.
- Solder plated version of industry standard TO-247AC package.



$$V_{CES} = 600V$$

$$V_{CE(on)} \text{ typ.} = 1.50V$$

$$@ V_{GE} = 15V, I_C = 60A$$

Benefits

- Generation 4 IGBT's offer highest efficiency available.
- IGBT's optimized for specified application conditions.
- Solder plated version of the TO-247 allows the reflow soldering of the package heatsink to a substrate material.
- Designed for best performance when used with IR HEXFRED & IR FRED companion diodes.



TO-247AC

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Breakdown Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	90	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	60	
I_{CM}	Pulsed Collector Current ①	120	
I_{LM}	Clamped Inductive Load Current ②	120	
V_{GE}	Gate-to-Emitter Voltage	± 20	V
E_{ARV}	Reverse Voltage Avalanche Energy ③	200	mJ
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	520	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	210	
T_J	Operating Junction and	-55 to + 150	$^\circ C$
T_{STG}	Storage Temperature Range		
	Soldering Temperature, for 10 seconds	300 (0.063 in. (1.6mm from case)	
	Mounting torque, 6-32 or M3 screw	10 lbf•in (1.1N•m)	
	Maximum Reflow Temperature ④	230 (Time above 183 $^\circ C$ should not exceed 100s)	$^\circ C$

Thermal Resistance

	Parameter	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case	—	0.24	$^\circ C/W$
$R_{\theta CS}$	Case-to-Sink, Flat, Greased Surface	0.24	—	
$R_{\theta JA}$	Junction-to-Ambient (Typical Socket Mount)	—	40	
$R_{\theta JA}$	Junction-to-Ambient (PCB Mount, Steady State)⑥	—	20	
Wt	Weight	6 (0.21)	—	g (oz)

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Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage	600	—	—	V	$V_{GE} = 0V, I_C = 250\mu A$
$V_{(BR)ECS}$	Emitter-to-Collector Breakdown Voltage ④	16	—	—	V	$V_{GE} = 0V, I_C = 1.0A$
$\Delta V_{(BR)CES}/\Delta T_J$	Temperature Coeff. of Breakdown Voltage	—	0.13	—	V/ $^\circ\text{C}$	$V_{GE} = 0V, I_C = 1.0mA$
$V_{CE(ON)}$	Collector-to-Emitter Saturation Voltage	—	1.5	1.8	V	$I_C = 60A, V_{GE} = 15V$
		—	1.7	—		$I_C = 90A, V_{GE} = 15V$
		—	1.5	—		$I_C = 60A, T_J = 150^\circ\text{C}$ See Fig.2, 5
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	6.0		$V_{CE} = V_{GE}, I_C = 250\mu A$
$\Delta V_{GE(th)}/\Delta T_J$	Temperature Coeff. of Threshold Voltage	—	-11	—	mV/ $^\circ\text{C}$	$V_{CE} = V_{GE}, I_C = 250\mu A$
g_{fe}	Forward Transconductance ⑤	36	69	—	S	$V_{CE} = 100V, I_C = 60A$
I_{CES}	Zero Gate Voltage Collector Current	—	—	250	μA	$V_{GE} = 0V, V_{CE} = 600V$
		—	—	2.0		$V_{GE} = 0V, V_{CE} = 10V, T_J = 25^\circ\text{C}$
		—	—	1000		$V_{GE} = 0V, V_{CE} = 600V, T_J = 150^\circ\text{C}$
I_{GES}	Gate-to-Emitter Leakage Current	—	—	± 100	nA	$V_{GE} = \pm 20V$

Switching Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions
Q_g	Total Gate Charge (turn-on)	—	290	340	nC	$I_C = 40A$
Q_{ge}	Gate - Emitter Charge (turn-on)	—	40	47		$V_{CC} = 400V$ See Fig. 8
Q_{gc}	Gate - Collector Charge (turn-on)	—	100	130		$V_{GE} = 15V$
$t_{d(on)}$	Turn-On Delay Time	—	42	—	ns	$T_J = 25^\circ\text{C}$ $I_C = 60A, V_{CC} = 480V$ $V_{GE} = 15V, R_G = 5.0\Omega$
t_r	Rise Time	—	66	—		
$t_{d(off)}$	Turn-Off Delay Time	—	310	360		
t_f	Fall Time	—	170	220		
E_{on}	Turn-On Switching Loss	—	0.30	—	mJ	Energy losses include "tail" See Fig. 10, 11, 13, 14
E_{off}	Turn-Off Switching Loss	—	4.6	—		
E_{ts}	Total Switching Loss	—	4.9	6.3		
$t_{d(on)}$	Turn-On Delay Time	—	39	—	ns	$T_J = 150^\circ\text{C}$, $I_C = 60A, V_{CC} = 480V$ $V_{GE} = 15V, R_G = 5.0\Omega$
t_r	Rise Time	—	66	—		
$t_{d(off)}$	Turn-Off Delay Time	—	470	—		
t_f	Fall Time	—	300	—		
E_{ts}	Total Switching Loss	—	8.8	—	mJ	See Fig. 13, 14
L_E	Internal Emitter Inductance	—	13	—	nH	Measured 5mm from package
C_{ies}	Input Capacitance	—	6050	—	pF	$V_{GE} = 0V$ $V_{CC} = 30V$ See Fig. 7 $f = 1.0MHz$
C_{oes}	Output Capacitance	—	360	—		
C_{res}	Reverse Transfer Capacitance	—	66	—		

Notes:

- ① Repetitive rating; $V_{GE} = 20V$, pulse width limited by max. junction temperature. (See fig. 13b)
- ② $V_{CC} = 80\%(V_{CES})$, $V_{GE} = 20V$, $R_G = 5.0\Omega$. (See fig. 13a)
- ③ Repetitive rating; pulse width limited by maximum junction temperature.
- ④ Pulse width $\leq 80\mu s$; duty factor $\leq 0.1\%$.
- ⑤ Pulse width $5.0\mu s$, single shot.
- ⑥ When mounted on 1" square PCB (FR-4 or G-10 Material). For recommended footprint and soldering techniques refer to application note #AN-994.
- ⑦ Refer to application note # 1023, "Surface Mounting of Larger Devices."

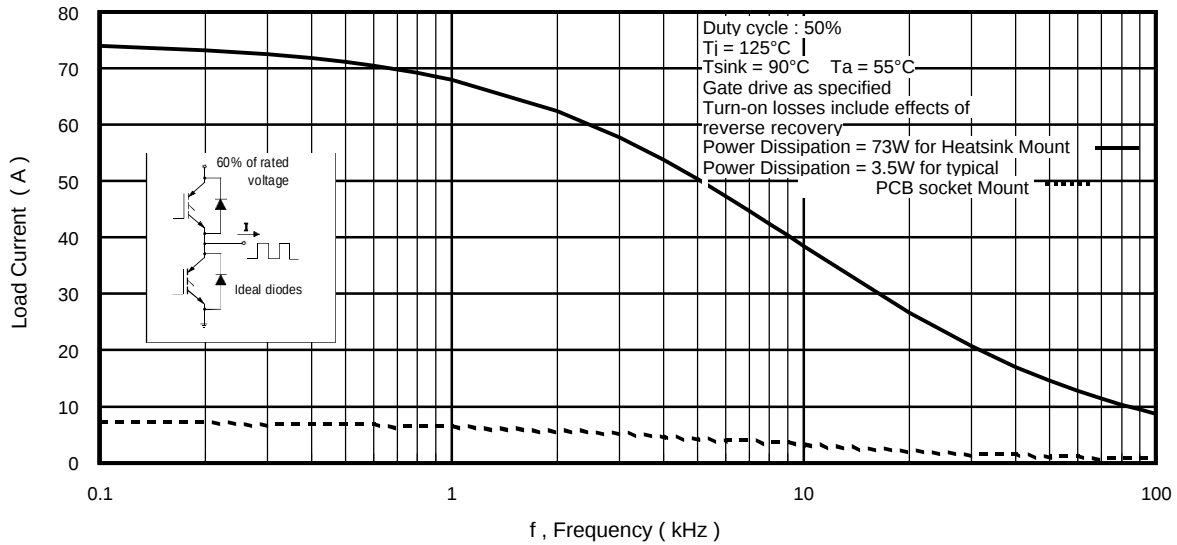


Fig. 1 - Typical Load Current vs. Frequency
 (For square wave, $I = I_{\text{RMS}}$ of fundamental; for triangular wave, $I = I_{\text{PK}}$)

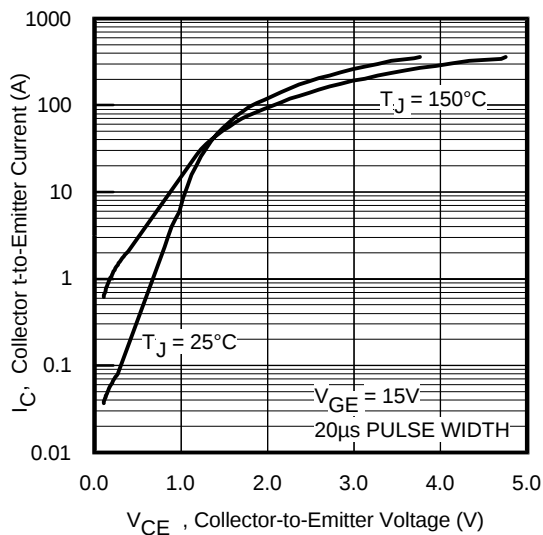


Fig. 2 - Typical Output Characteristics

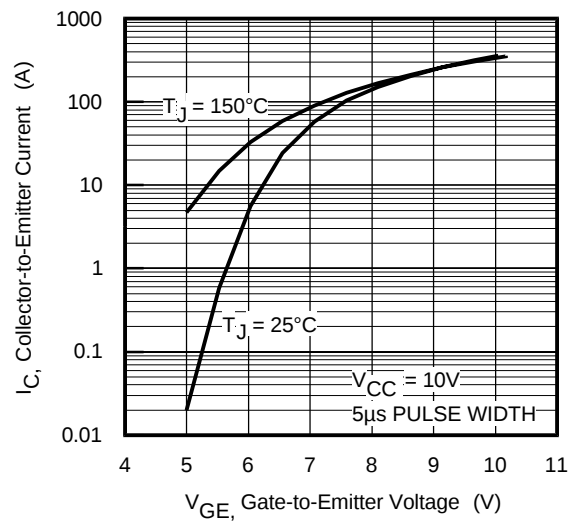


Fig. 3 - Typical Transfer Characteristics

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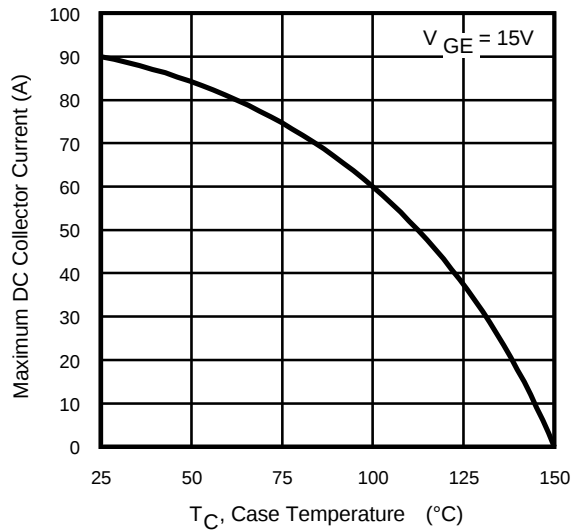


Fig. 4 - Maximum Collector Current vs. Case Temperature

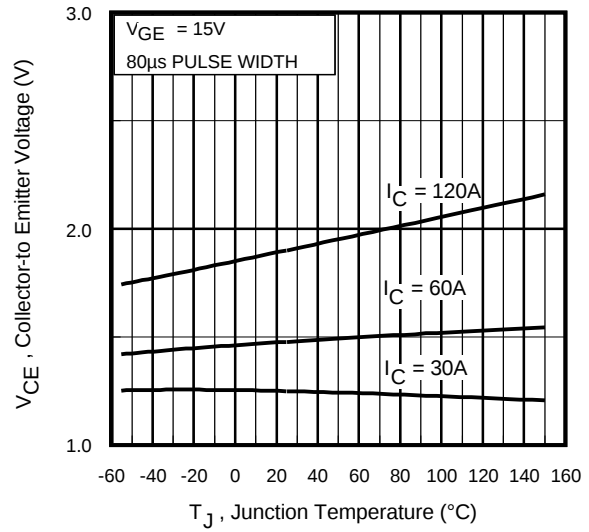


Fig. 5 - Typical Collector-to-Emitter Voltage vs. Junction Temperature

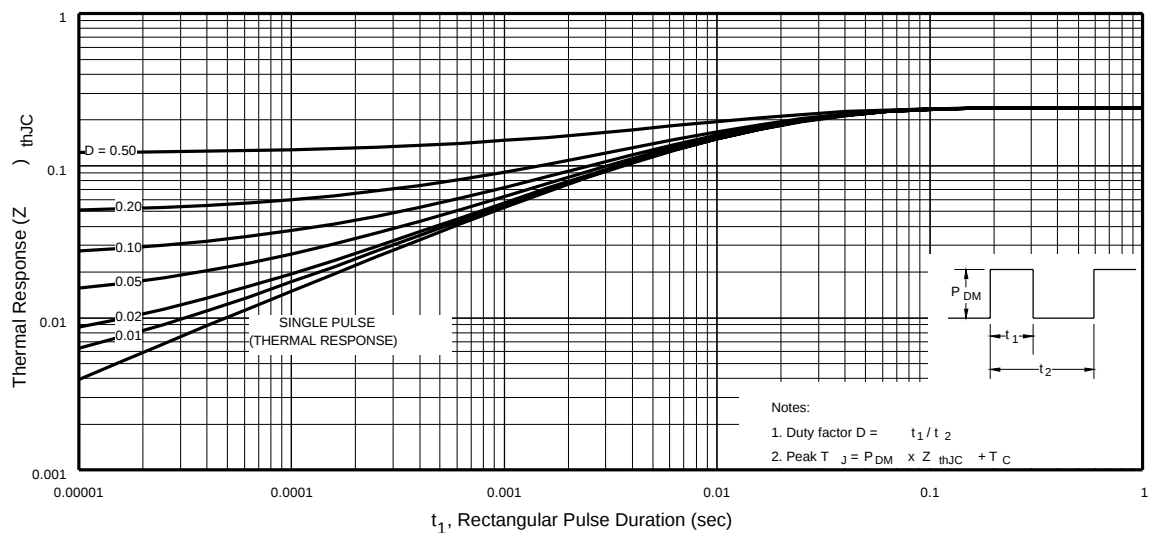
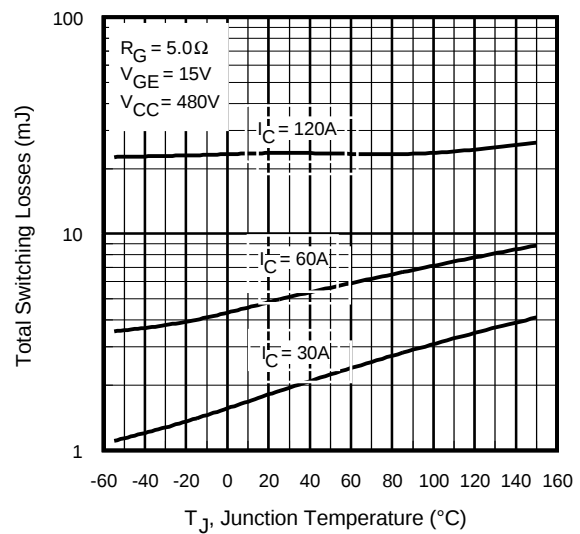
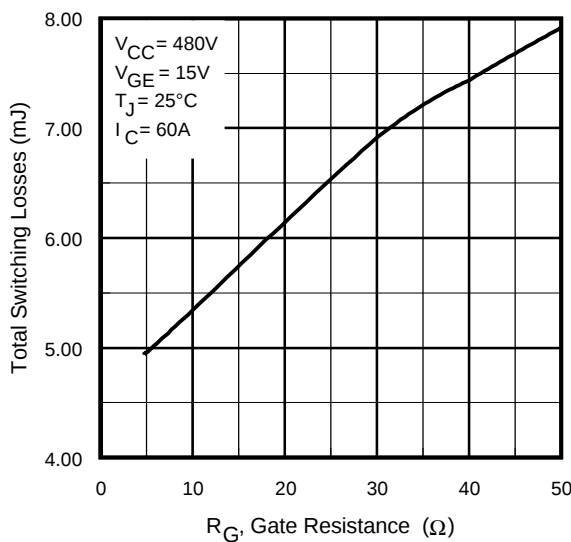
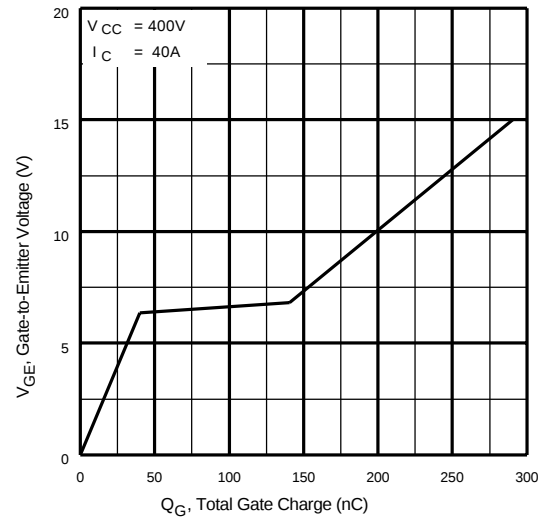
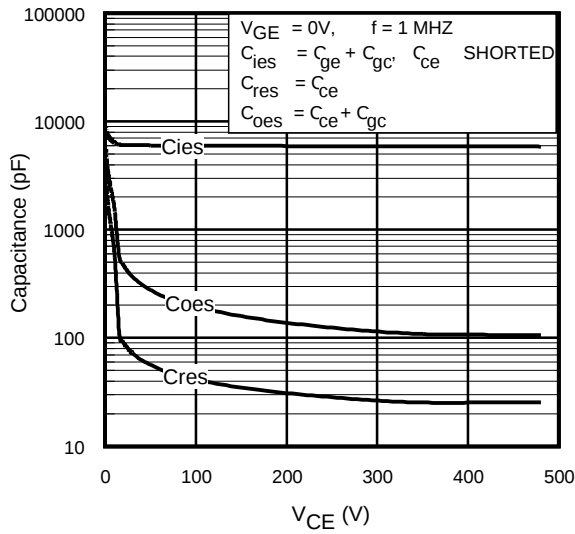


Fig. 6 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



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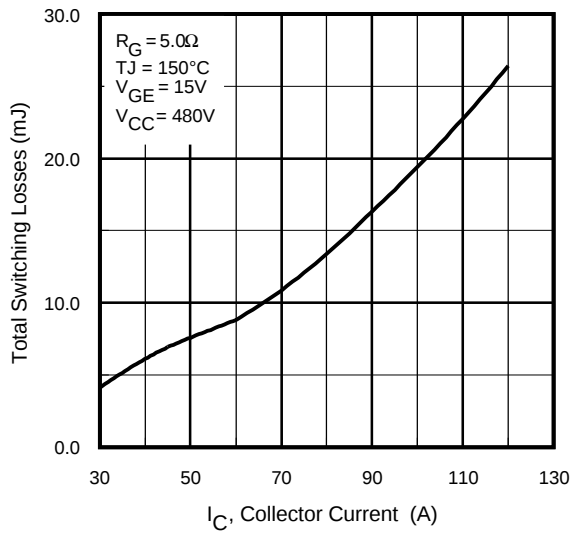


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

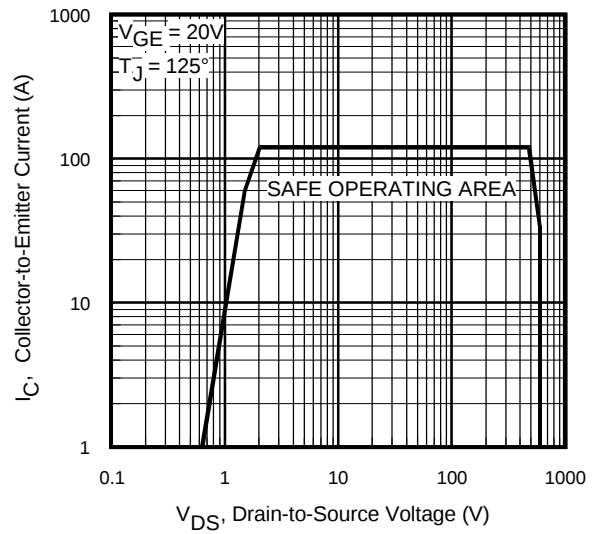


Fig. 12 - Turn-Off SOA

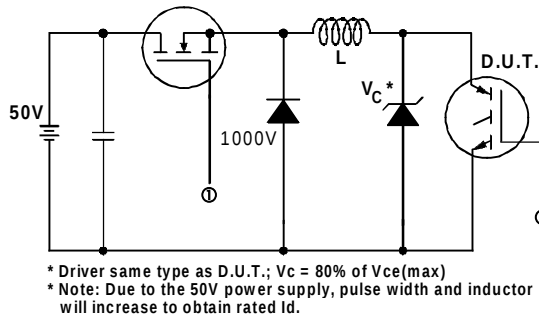


Fig. 13a - Clamped Inductive Load Test Circuit

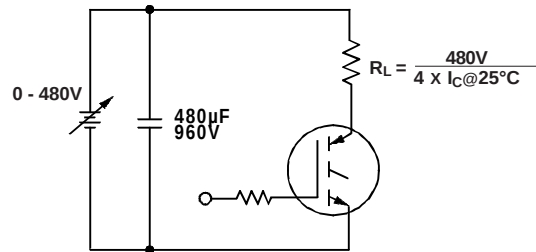


Fig. 13b - Pulsed Collector Current Test Circuit

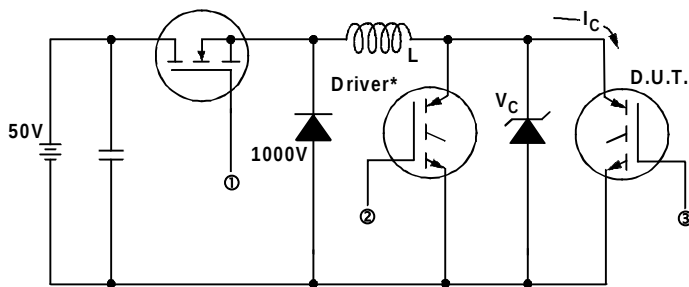


Fig. 14a - Switching Loss Test Circuit

* Driver same type as D.U.T., $V_C = 480V$

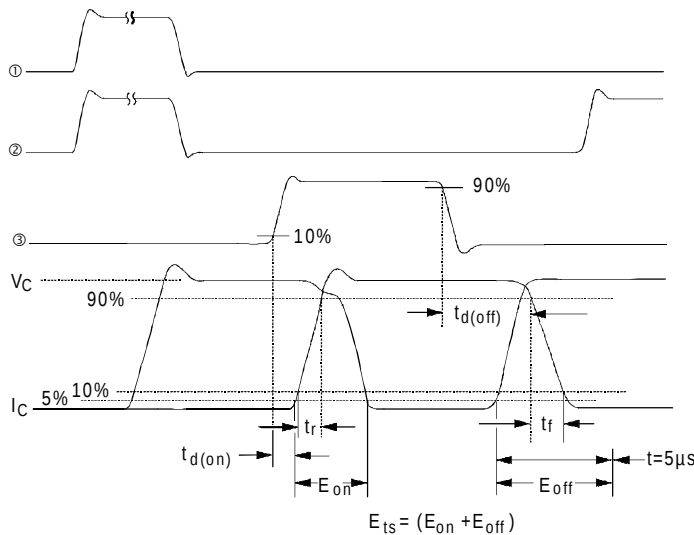


Fig. 14b - Switching Loss Waveforms

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The technical drawing shows two views of a mechanical component:

- Front View (Left):** A rectangular part with a central circular hole. Dimensions include overall width 15.90 (.626), inner width 15.30 (.602), and height 20.30 (.800). The hole has a diameter of 3.65 (.143) and a depth of 5.50 (.217). There are three vertical slots at the bottom, each 2.40 (.094) wide and 14.20 (.559) deep. The distance between the centers of the slots is 3.40 (.133).
- Side View (Right):** Shows the profile of the part with a total height of 5.30 (.209). It features a top flange 4.70 (.185) thick and a main body 2.50 (.089) thick. A central slot is 1.50 (.059) wide.

Key features and tolerances:

- Hole:** Diameter 3.65 ± .010 (M), Depth 5.50 ± .010 (M).
- Slots:** Width 2.40 ± .010 (M), Depth 14.20 ± .010 (M).
- Flanges:** Top flange thickness 4.70 ± .010 (M), Main body thickness 2.50 ± .010 (M).

1 DIMENSIONS & TOLERANCING
PER ANSI Y14.5M, 1982.
2 CONTROLLING DIMENSION : INCH.
3 DIMENSIONS ARE SHOWN
MILLIMETERS (INCHES).
4 CONFORMS TO JEDEC OUTLINE
TO-247AC.

1 - GATE
2 - COLLECTOR
3 - EMITTER
4 - COLLECTOR

* LONGER LEADED (20mm)
VERSION AVAILABLE (TO-247AD)
TO ORDER ADD "-E" SUFFIX
TO PART NUMBER

Dimensions in Millimeters and (Inches)

Data and specifications subject to change without notice.
This product has been designed and qualified for the Industrial market.
Qualification Standards can be found on IR's Web site.

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